

# Filter Design Guidance for UCC12050 EMI Mitigation

**Input Filter Component Considerations**  
**EMI Mitigation Techniques**

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# Ferrite Bead Selection

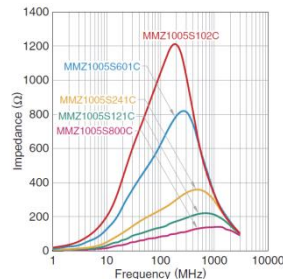
- Ferrite beads are selected based upon:

- Current rating – 120 mA is the worst case input current expected for UCC12050. Select input ferrite beads with minimum 150 mA. Contact the bead manufacturer and ask for DC bias curves (examples shown on following slides).

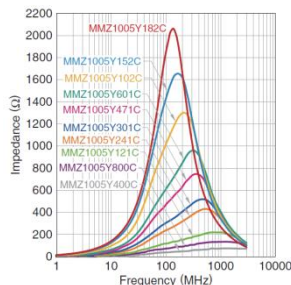
$$I_{IN} = \frac{P_{O(MAX)}}{n \times V_{IN(MIN)}} = \frac{0.5 W}{0.6 \times 4.5 V} = 225 mA$$

- Impedance (Z) vs frequency (F) – Impedance response can be very high over a narrow frequency band or not as high over a wider frequency band (examples shown below). Response is based on material type . Start with highest impedance over widest frequency band of interest, as shown on following slide. Once we determine a specific frequency where radiated EMI is problematic, we may adjust the ferrite bead selection to be optimal around that frequency. Examples of impedance vs frequency:

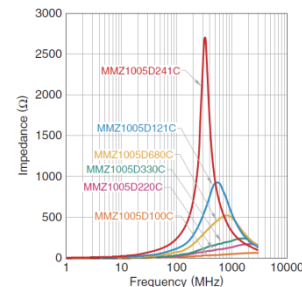
MMZ1005S series



MMZ1005Y series

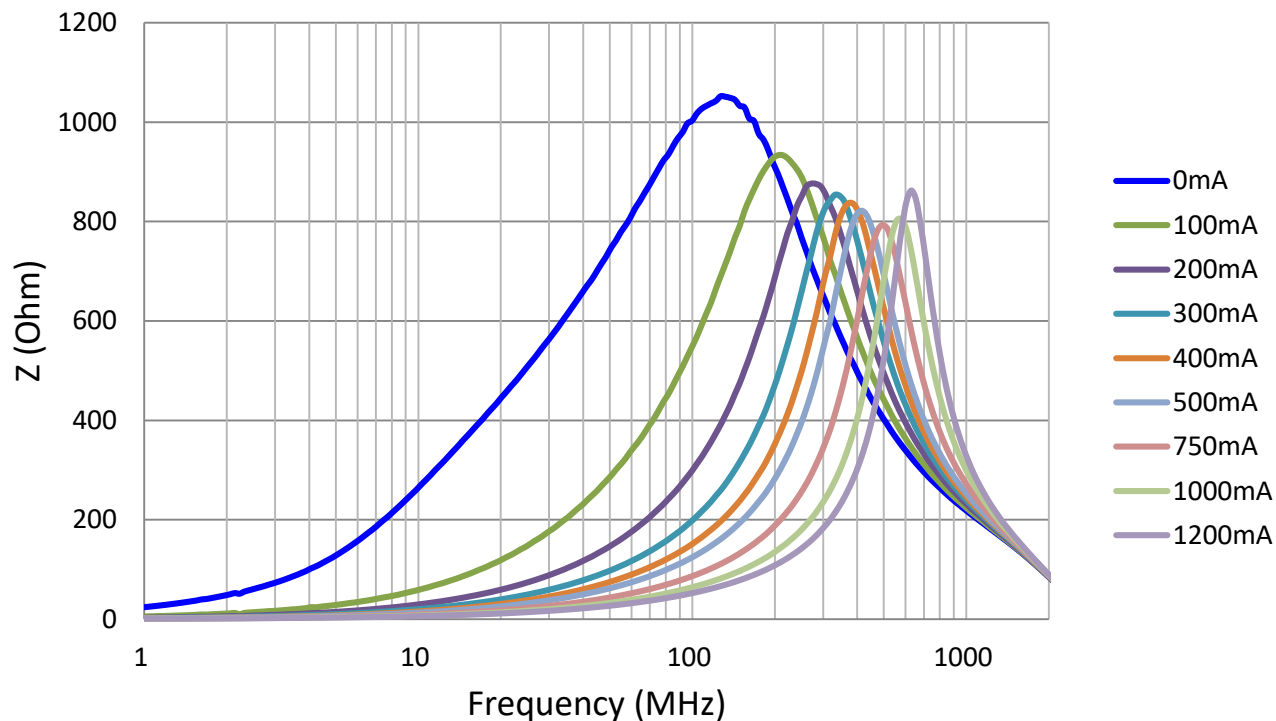


MMZ1005D series

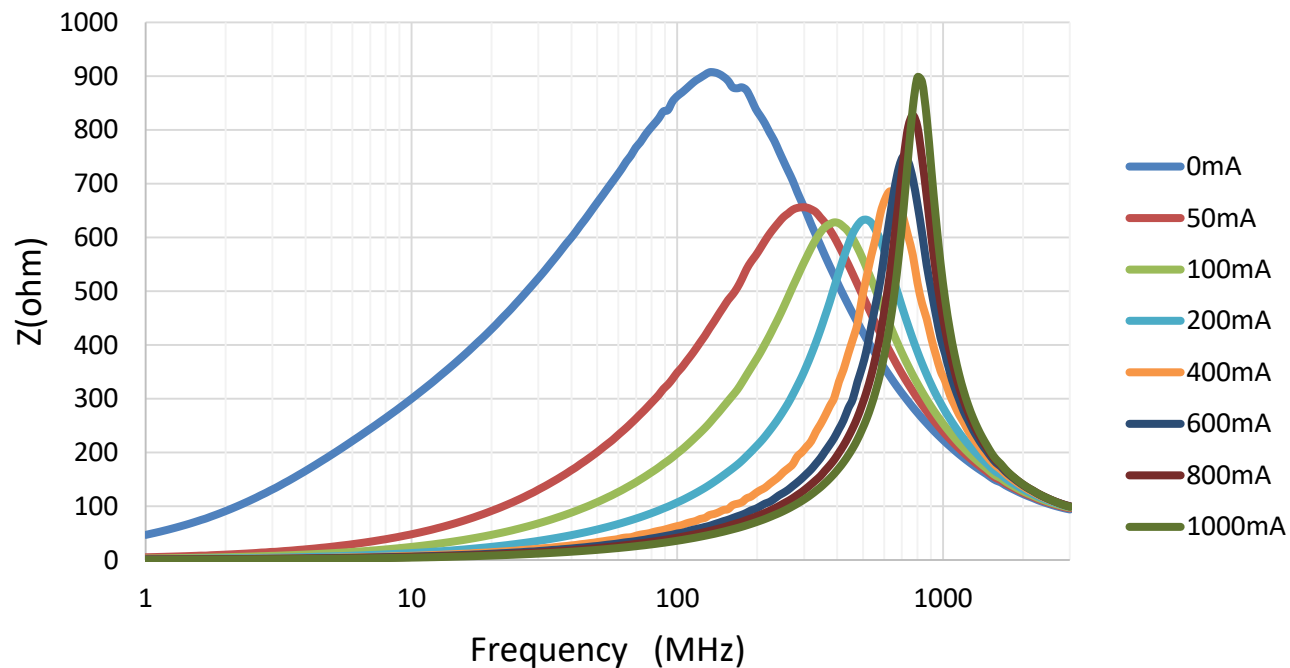


- DC Resistance (DCR) – Important for overall efficiency but from EMI point of view this should be the last parameter considered.

# BLM18SP102SH, DC Bias Effect



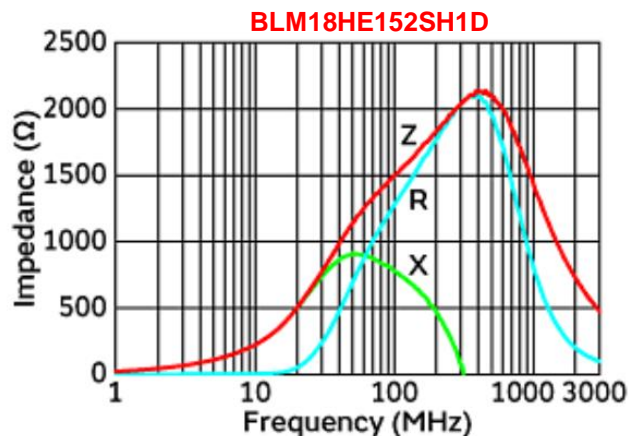
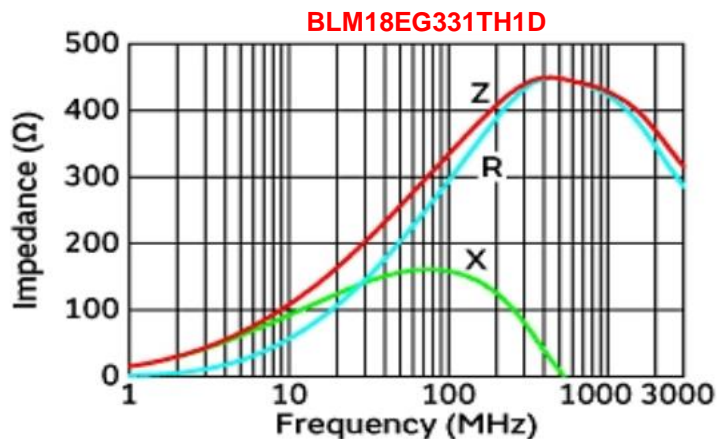
# BLM18KG102SH, DC Bias Effect



# UCC12050, Initial Bead Selection

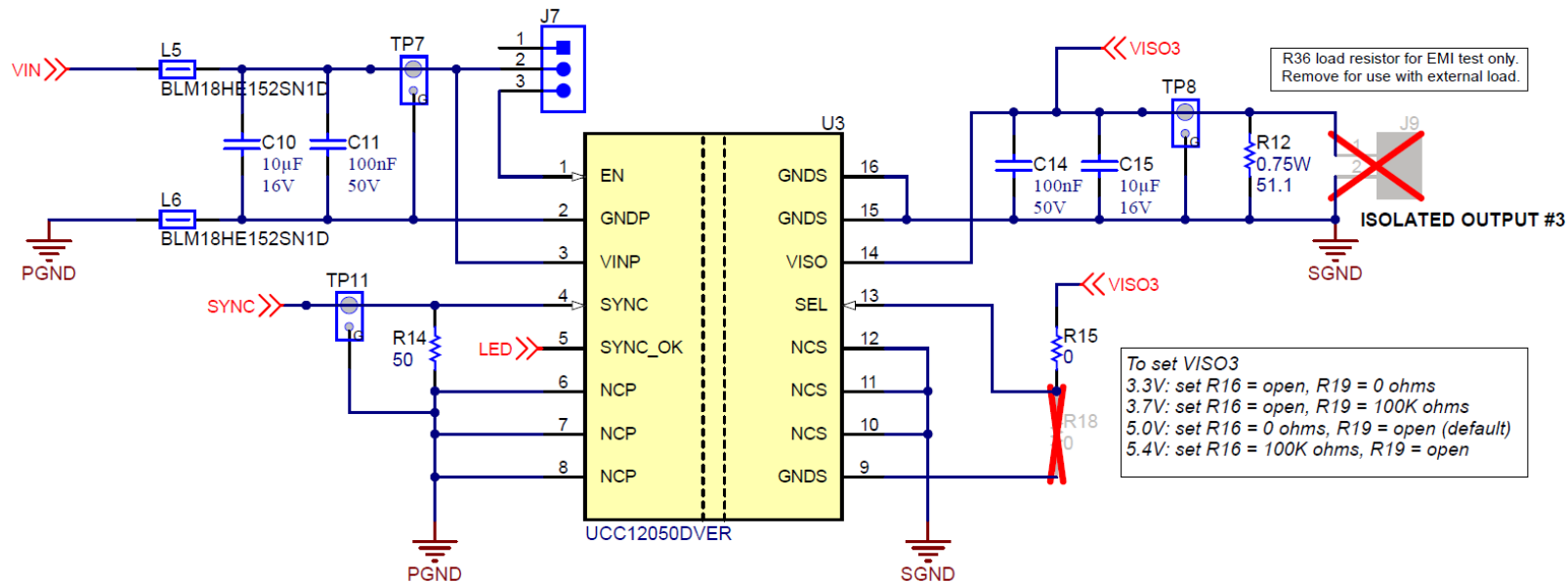
- CISPR 32, Class B frequency of interest:  $30\text{ MHz} < F < 1\text{ GHz}$  – Select beads that have high Z over your frequency where the EMI is failing.
- Trade off between  $I_{\text{MAX}}$ , Z, F, DCR

Part	MFR	Z (100MHz)	Z(300MHz)	Z(1GHz)	$I_{\text{MAX}}$	Temp	DCR	Pkg	Comment
BLM18EG331TH1D	Murata	330 $\Omega$	-	450 $\Omega$	500 mA	-55 $^{\circ}\text{C} < T < 125\text{ }^{\circ}\text{C}$	210 m $\Omega$	0603	AEC-Q200
BLM18HE152SH1D	Murata	1.5 k $\Omega$	-	1.5 k $\Omega$	500 mA	-55 $^{\circ}\text{C} < T < 125\text{ }^{\circ}\text{C}$	500 m $\Omega$	0603	AEC-Q200



- Start with BLM18HE152SH1D
- Higher impedance
- Higher DCR

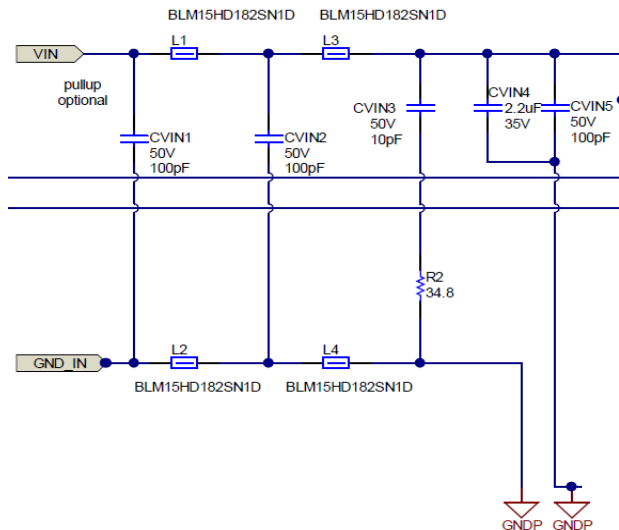
# UCC12050, Input Ferrite Bead Example





## • Ferrite Beads for EMI Mitigation:

- Use of ferrite beads work best where there is a cable interface to the UCC12050
- We have a cable interface on the input side from the 5V dc VIN – Ferrite beads, L5, L6 are used on the input side
- We have no cable interface on the output side because the load (R12) is directly on the PCB – no ferrite beads are necessary in this case. If the load to the UCC12050 is off the PCB and uses a cable interface, ferrite beads can be used on the output side, similar to the input side.

# UCC12050, Ferrite Bead + MLCC EMI Filter Example

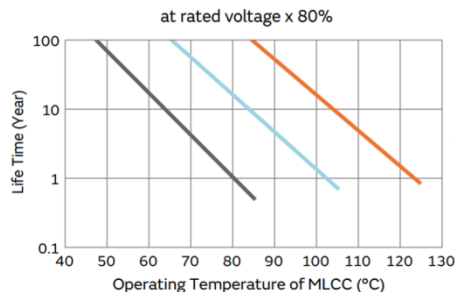


Murata GCM Type, COG, 0402, Capacitor Range

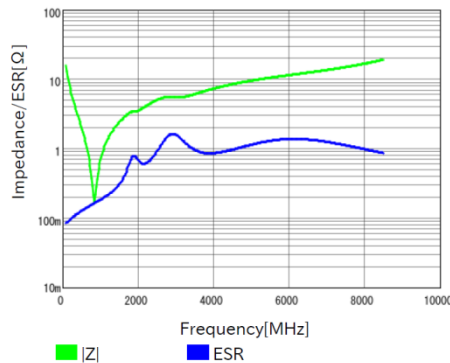
Maximum operating temperature	LxW	Rated Voltage	Capacitance												Capacitance range
			pF					μF							
			0.1	1	10	100	1000	0.01	0.1	1	10	100	1000		
125°C	1.0x0.5mm	50Vdc													0.10pF - 1000pF
150°C	1.0x0.5mm	50Vdc													0.10pF - 1000pF

High dielectric constant type

Available Under development



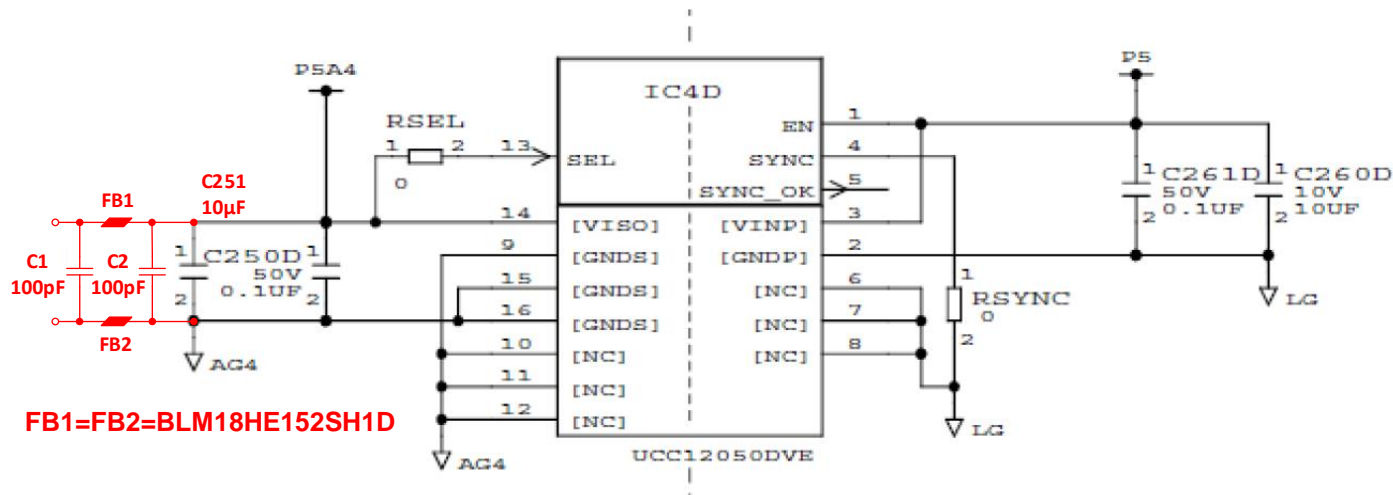
COG, 0402, 100pF, SRF~1GHz



## • Ferrite Beads used with MLCC for EMI Filter Design:

- Ferrite Beads used with MLCC capacitors to form complex EMI filter networks
- Apply <80% rated voltage
- 50 V, 0402 input EMI filter capacitors easily meet 80% voltage rating requirement
- Next level of EMI performance is [Murata NFM low ESL, 3 terminal EMI filter MLCC](#)

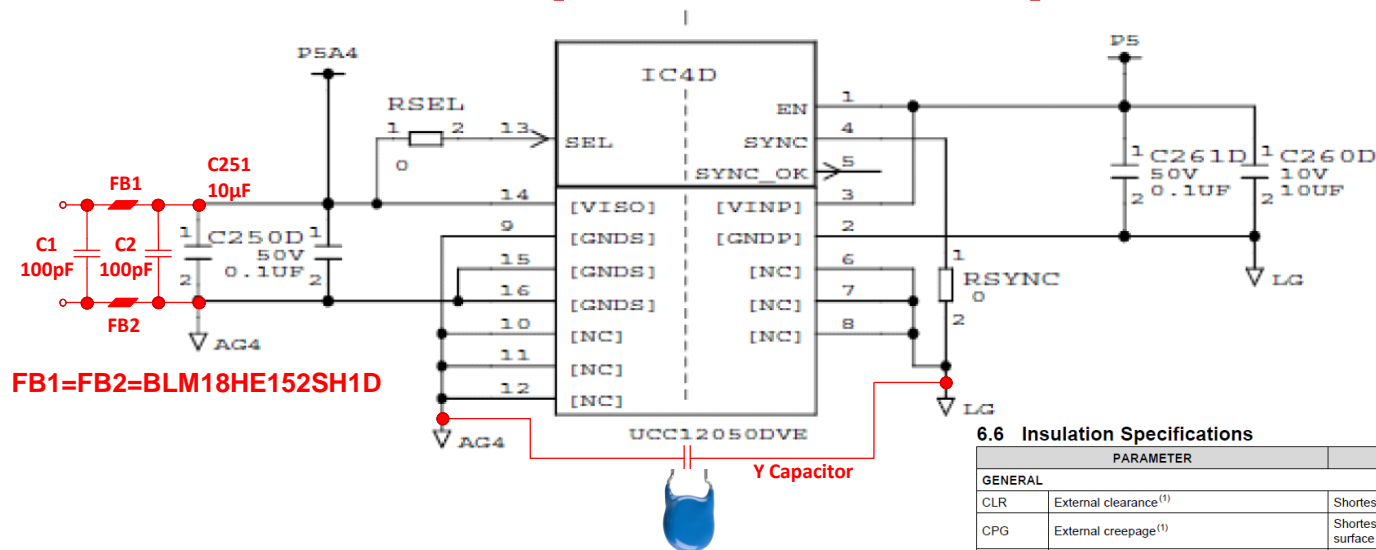
# UCC12050 Output EMI Filter: Example



- **Ferrite Beads used with MLCC for EMI Filter Design:**

- Output ferrite beads help when the load is dynamic (switching, clocks, high speed digital, etc)
- **When PCB is properly designed, no ferrite beads will be required to pass CISPR32, Class B**
- Above recommendation is to try and improve failed CISPR 32, Class B
- Assure the GND plane is being used effectively
- C1 and C2 may not be needed but can be tested as shown above

# UCC12050 Y-Capacitor: Example



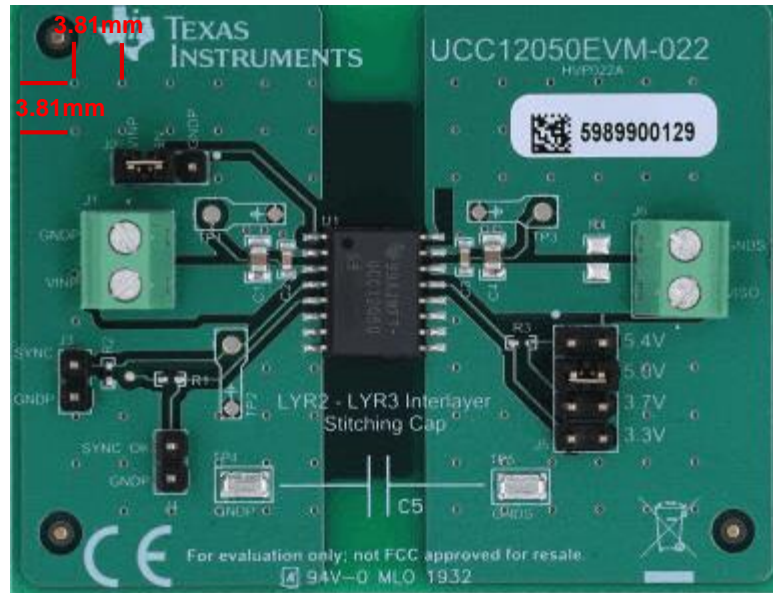
## • Addition of external primary-secondary, Y-capacitor:

- **Used to reduce CM noise, improve EMI**
- Provides low impedance path across transformer
- Reduces common mode noise
- Choose capacitor with similar voltage rating as UCC12050
- TDK [CK45 series](#) is one example up to 3 kV rating

## 6.6 Insulation Specifications

PARAMETER		TEST CONDITIONS	VALUE	UNIT
<b>GENERAL</b>				
CLR	External clearance <sup>(1)</sup>	Shortest terminal-to-terminal distance through air	> 8	mm
CPG	External creepage <sup>(1)</sup>	Shortest terminal-to-terminal distance across the package surface	> 8	mm
DTI	Distance through the insulation	Minimum internal gap (internal clearance)	> 120	µm
CTI	Comparative tracking index	DIN EN 60112 (VDE 0303-11); IEC 60112	> 600	V
Material group		According to IEC 60664-1	I	
Overvoltage Category		Rated mains voltage ≤ 300 V <sub>RMS</sub>	I-IV	
		Rated mains voltage ≤ 600 V <sub>RMS</sub>	I-IV	
		Rated mains voltage ≤ 1000 V <sub>RMS</sub>	I-III	
<b>DIN V VDE V 0884-11:2017-01<sup>(2)</sup> (Planned Certification Targets)</b>				
V <sub>ORM</sub>	Maximum repetitive peak isolation voltage	AC voltage (bipolar)	1414	V <sub>PK</sub>
V <sub>IOWM</sub>	Maximum working isolation voltage	AC voltage (sine wave) Time dependent dielectric breakdown (TDDb) test	1000	V <sub>RMS</sub>
		DC voltage	1414	V <sub>DC</sub>
V <sub>OTM</sub>	Maximum transient isolation voltage	V <sub>TEST</sub> = V <sub>OTM</sub> , t = 60s (qualification); V <sub>TEST</sub> = 1.2 × V <sub>OTM</sub> , t = 1s (100% production)	7071	V <sub>PK</sub>
V <sub>IOSM</sub>	Maximum surge isolation voltage <sup>(3)</sup>	Test method per IEC 62368-1, 1.2/50 µs waveform, V <sub>TEST</sub> = 1.6 × V <sub>IOSM</sub> = 10000 V <sub>PK</sub> (qualification)	6250	V <sub>PK</sub>

# Stitch Vias: TI UCC12050EVM-022 PCB



- PCB needs more vias and possibly larger size:
  - Should use TI UCC12050EVM-022 as guideline

- UCC12050EVM=022 via pattern
  - 12 mil hole size, 30 mil outer ring
  - 3.81 x 3.81mm via grid
  - See [UCC12050EVM-022 User Guide](#) for additional guidance on inner layer connections

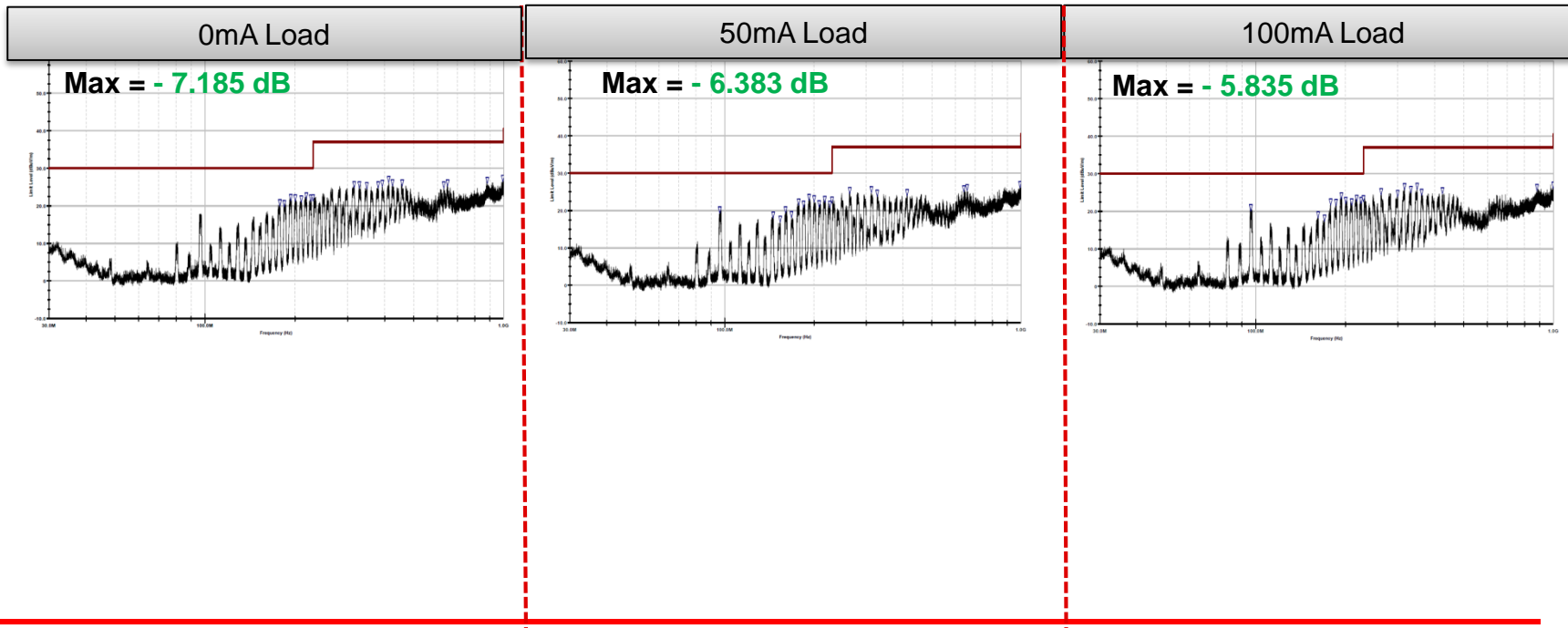
# EMI:

EVM configuration: no ferrite beads , no LDO, no stitch capacitors, on 2 layer PCB

Tested to CISPR32 Limit, in 10m chamber, on same day, in same certified lab.

- **Lower radiated emissions with SSM** – **Passed** CISPR32, 10m chamber with 0mA, 50mA, 100mA loads.
- UCC12050 has >5dB margin

UCC12050



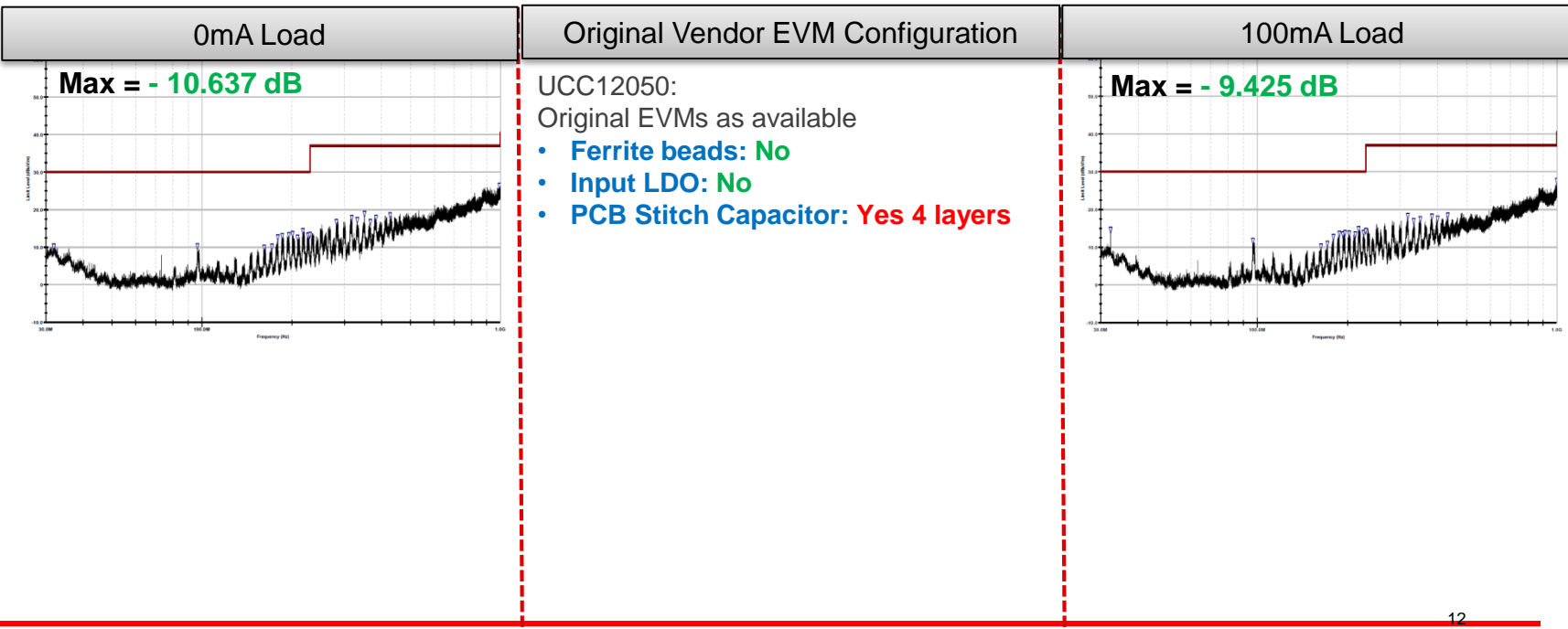
# EMI:

UCC12050EVM-022

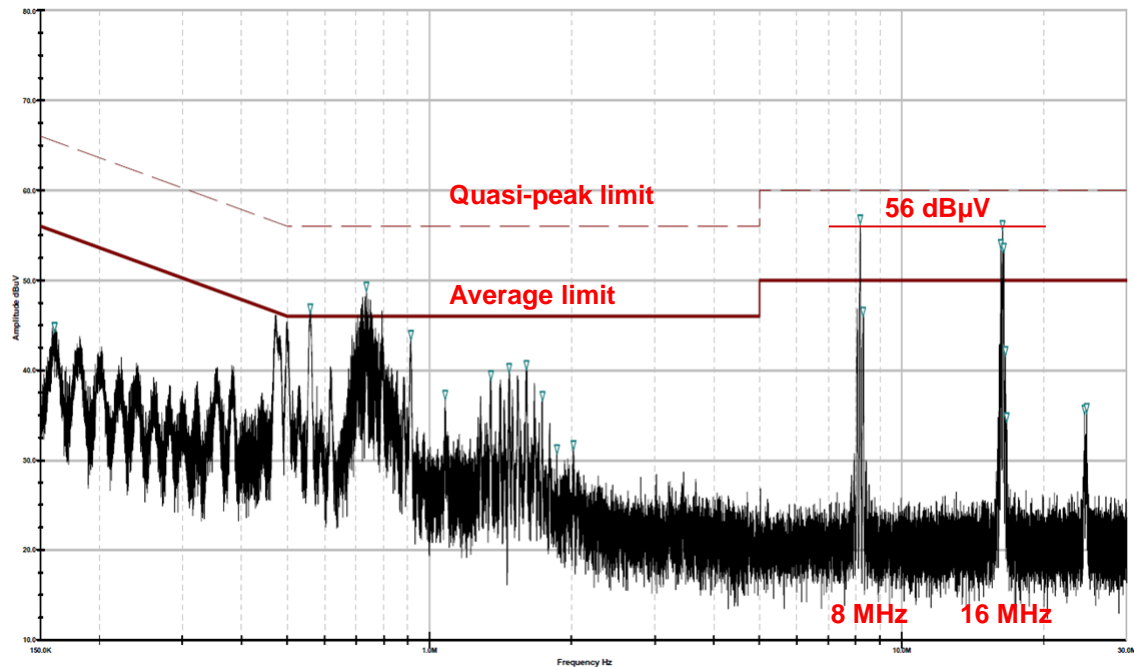
Tested to CISPR32, Class B Limit, in 10m chamber

- **Lower radiated emissions with SSM and integrated PCB stitch capacitor** – Passed CISPR32, Class B, 10m chamber with 0mA, and 100mA loads.
- UCC12050 has >9dB margin.

UCC12050

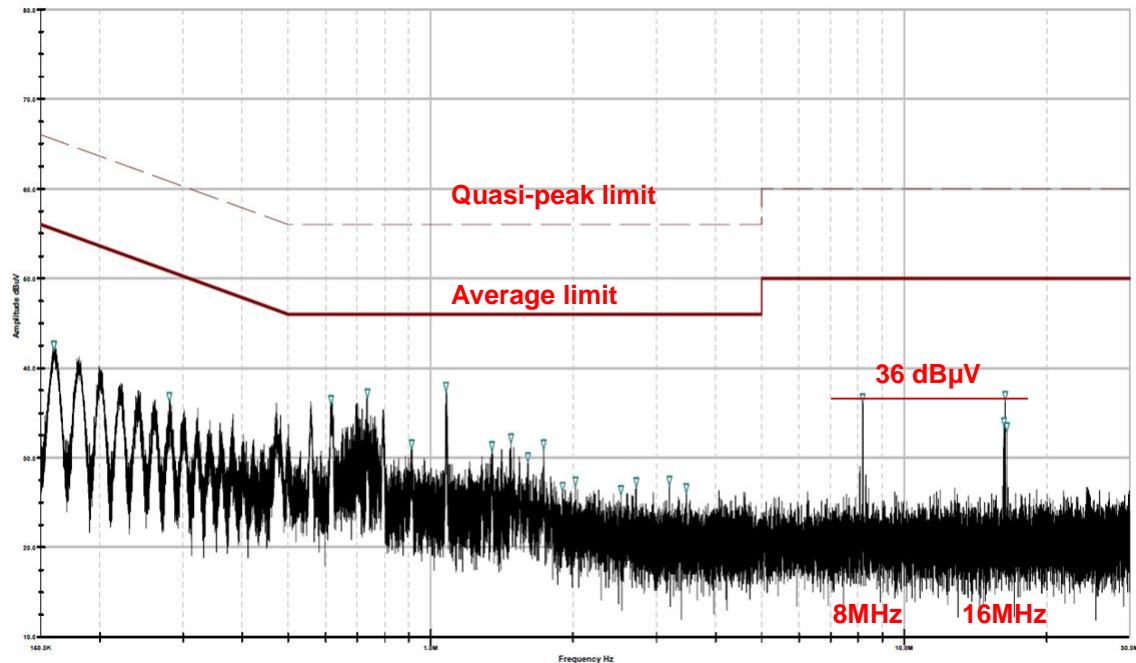


# UCC12050 CISPR 32, Class B Conducted Emissions



- CISPR32, Class B
  - $150\text{kHz} < F < 30\text{MHz}$
- No board level EMI filter added
- No ferrite beads

# UCC12050 CISPR 32, Class B Conducted Emissions



- CISPR32, Class B
  - $150 \text{ kHz} < F < 30 \text{ MHz}$
- No board level EMI filter added
- 2x input (VINP, GNDP) ferrite beads added
  - Murata BLM15HD182SN1
  - FB rating:  $1.8 \text{ k}\Omega$  at  $100 \text{ MHz}$
  - 20 dB reduction at 8 MHz and 16 MHz